

December 2006

ES3A - ES3J

Fast Rectifiers

Features

- · For surface mount applications.
- · Glass passivated junction.
- · Low profile package.
- Easy pick and place.
- · Built-in strain relief.
- · Superfast recovery times for high efficiency.



SMC/DO-214AB Color Band Denotes Cathode

Absolute Maximum Ratings * T_a = 25°C unless otherwise noted

| Symbol | Parameter | Value | | | | Units | |
|----------------------------------|---|-------------|------|------|------|-------|--------|
| | | ES3A | ES3B | ES3C | ES3D | ES3J | Ullits |
| V_{RRM} | Maximum Repetitive Reverse Voltage | 50 | 100 | 150 | 200 | 600 | V |
| I _{F(AV)} | Average Rectified Forward Current, .375" lead length @ T _A =75°C | 3.0 | | | А | | |
| I _{FSM} | Non-repetitive Peak Forward Surge Current 8.3 ms Single Half-Sine-Wave | 100 | | А | | | |
| T _{J,} T _{STG} | Operating Junction and Storage Temperature Range | -50 to +150 | | °C | | | |
| P_{D} | Power Dissipation | 1.66 | | W | | | |

^{*}These ratings are limiting values above which the serviceability of any semiconductor device may by impaired.

Thermal Characteristics

| Symbol | Parameter | Value | Units |
|-----------------|---|-------|-------|
| $R_{\theta JA}$ | Thermal Resistance, Junction to Ambient * | 47 | °C/W |
| $R_{\theta JL}$ | Thermal Resistance, Junction to Lead * | 12 | °C/W |

^{*} Device mounted on FR-4 PCB 0.013 mm.

Electrical Characteristics T_C = 25°C unless otherwise noted

| Symbol | Parameter | Value | Units |
|-----------------|---|-------|-------|
| V _F | Forward Voltage @ I _F = 3.0 A | 0.95 | V |
| T _{rr} | Reverse Recovery Time $I_F = 0.5 \text{ A}, I_R = 1.0 \text{ A}, I_{RR} = 0.25 \text{ A}$ | 20 35 | ns |
| I _R | Reverse Current @ rated V_R $T_A = 25^{\circ}C$ $T_A = 100^{\circ}C$ | - | uA |
| СТ | Total Capacitance $V_R = 4.0 \text{ V}, f = 1.0 \text{ MHz}$ | 45 | pF |

Typical Performance Characteristics

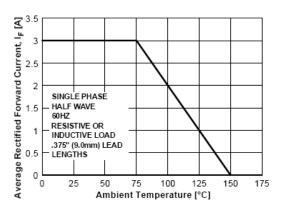


Figure 1. Foward Current Deration Curve

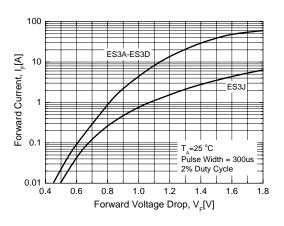


Figure 2. Foward Voltage Characteristics

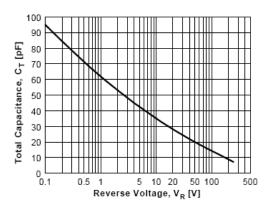


Figure 3. Total Capacitance

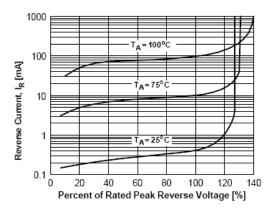
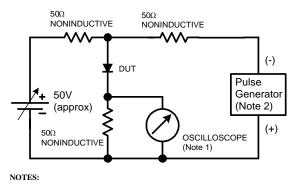
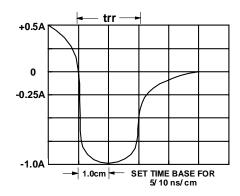


Figure 4. Reverse Current vs Reverse Voltage



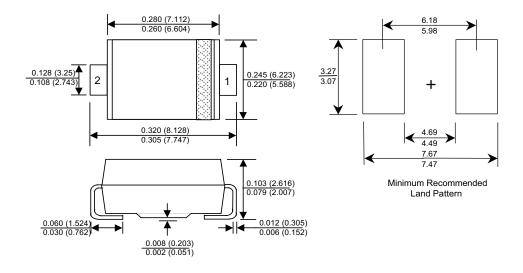
- 1. Rise time = 7.0 ns max; Input impedance = 1.0 megaohm 22 pf.
- 2. Rise time = 10 ns max; Source impedance = 50 ohms.



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Package Dimensions

SMC / DO - 214AB



Dimensions in Inches(Millimeters)

UniFET™

 VCX^{TM}

Wire™



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UHC®

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|--------------------------|------------------------|---|
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